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# The 42nd International Conference on Thermoelectrics

May 17 - 21, 2026

Houston, Texas U.S.A

Hyatt Regency Downtown Houston

#### **Conference Chairs:**

Zhifeng Ren, University of Houston
Shuo Chen, University of Houston

Abstract Submission Deadline: 01/31/2026
Early Registration Deadline: 02/28/2026
Hotel Reservation Deadline: 04/27/2026

#### Welcome Message

Houston is renowned as the "Energy Capital of the World." Heat and electricity are undoubtedly two most essential forms of energy. In May 2026, we are honored to host the 42nd International Conference on Thermoelectrics (ICT) — for the first time in Houston. Following conference tradition, we will include all areas of thermoelectric research: from computational and theoretical work to experimental studies; from materials to modules and devices. In addition, we aim to introduce new topics in thermal management materials and devices, such as high thermal conductivity materials and innovative designs for efficient heat transfer across all scales, and also very low thermal conductivity for thermal insulation to increase the energy system efficiency. We highly welcome presentations from academia and industry, hoping these topics will inspire fresh ideas for discovering better materials and improving the energy conversion efficiencies to harness the abundant thermal energy. We look forward to engaging discussions and insightful outcomes at ICT 2026 in Houston!

First Announcement



## Topics:

- Theory & computation
- Thermoelectric materials
- Materials for thermal management



Measurements & characterizations

Contact: info@ict2026houston.com

Website: www.ict2026houston.com

- Thermoelectric modules
- Systems & industrial applications
- Summer School (05/17/2026)

### International Advisory Board: — in progress

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# Registration

	Registration	Early Registration (By February 28, 2026)	Regular Registration (By March 31, 2026)	Late Registration (After April 1, 2026)
	Regular Participant	USD 800	USD 900	USD 1,000
A STATE OF	Student	USD 300	USD 350	USD 400

# **Sponsorships**

Sponsorships are critical to the success of ICT 2026. Partnering allows for reduced registration fees, assistance to participants who could not otherwise afford to attend and for student travel grants. In exchange, ICT will increase sponsor's visibility both pre- and post-conference by formally recognizing the contribution in electronic and printed materials and providing time to address participants in formal sessions and events. Several \$25,000 Contributing Sponsors are being solicited for overall conference support. Advertising and in-kind opportunities are also available.

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